

ABSTRACT OF THE DISCLOSURE

In a leadframe packaging structure, a leadframe includes a plurality of first leads, a plurality of second leads, and a die pad. The first leads define a chip-bonding region in which is arranged the die pad. The second leads extend and terminate into a plurality of contact pads in the chip-bonding region. An adhesive tape further is bonded on bottom surfaces of the contact pads. A chip is bonded on the die pad. At least a passive device is mounted between and electrically connects the contact pads. A plurality of bonding wires respectively connect the chip, the passive device, and the first and second leads. An encapsulant material encapsulates the chip, the passive device, and the bonding wires.

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